



8th Micro/Nano-Electronics Packaging & Assembly, Design and Manufacturing Forum

Conference & Exhibition organized by IMAPS

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Call for Papers

Deadline february 28th , 2020

WTC Grenoble, France

May 27-28, 2020



"Bringing closer Design, Semiconductor, Assembly & Packaging communities"

General chair: Alexandre Val , Technical Chairs: Jean-Luc Diot, Michel Garnier, Romain Coffy & Gilles Simon

Abstracts are requested on the following topics (350 words min., one page max):

- **Advanced Packaging:** 2.5/3D Packaging, TSVs, interposers, wafer level packaging, fan-out WLP, embedded IC packages, substrates (flexible, ceramic, laminate), PCB
 - **CAD and tools for I/O placement for advanced packaging,** design for reliability, IC and package co-design, opto. & RF package design, thermal & mechanical modeling & simulation
 - **Digital deep submicron technologies for scaling nodes, MEMS, sensors, actuators, RF miniaturization, smart system packaging & heterogeneous integration**
 - **Innovative packaging for emerging and growing applications:** photovoltaic, wearable, medical electronics, bio-MEMS, Lab-on-chip power, pixelated & μ LEDs, photonics, optoelectronics, etc...
 - **Materials** (adhesives, underfills, molding, dielectrics...), **equipment's and processes**
 - **Emerging technologies and novel approaches :** microfluidics, Carbon Nano-Tubes, nanoscale integration
 - **Assembly manufacturing (BGA/CSP/QFP/QFN,** flux, cleaning, dispensing, coating,...) and business aspects of the industry
 - **Reliability, wear out, test and characterization,** electromigration, thermal management, power signal integrity
 - **Advanced interconnections:** flip-chip, interconnections for advanced CMOS process nodes, WLP metallurgies, bumping techniques, non-traditional interconnections, PCB solutions, optical connections
- Your submission must include the mailing address, business telephone number and email address and the content must be without commercial information.
- Address your abstract to imaps.france@imapsfrance.org
- Authors will be notified of paper acceptance with instructions for publication before **March 9th, 2020**
- Authors will be invited to submit a paper for proceedings publication (2 to 6 pages) before **April 14th, 2020**
- At the discretion of the program committee, submitted abstracts may be considered for poster presentation,
- Presentations following IMAPS template before **April 27th, 2019**